

***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

Applicants: Lopatin, *et al.*

Title: METHOD OF USING TERNARY  
COPPER ALLOY TO OBTAIN A  
LOW RESISTANCE AND LARGE  
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

**AMENDMENT AND REPLY UNDER 37 CFR 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Examiner Nadav:

This communication is responsive to the Non-Final Office Action dated April 23, 2007, concerning the above-referenced patent application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this document.

**Remarks/Arguments** begin on page 6 of this document.

Please amend the application as follows: